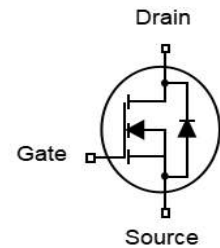


## Features

- N-Channel
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5\text{ V}$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Pb-free lead plating; RoHS compliant
- 100% EAS Tested

$V_{DS}$	100	V
$R_{DS(on),TYP}@ V_{GS}=10\text{ V}$	6.8	m $\Omega$
$I_D$	85	A

**TO-220**


Part ID	Package Type	Marking	Packing
ZTG068N10	TO-220	ZTG068N10	1000pcs/Tape

## Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (<math>T_c=25^\circ\text{C}</math> Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	100	V	
$T_J$	Maximum Junction Temperature	150	$^\circ\text{C}$	
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 3)	$T_c = 25^\circ\text{C}$ 340	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous (Note 2)	$T_c = 25^\circ\text{C}$	85	A
		$T_c = 100^\circ\text{C}$	58	A
$P_D$	Maximum Power Dissipation	104	W	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	1.2	$^\circ\text{C/W}$	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	62	$^\circ\text{C/W}$	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 1)	330	mJ	

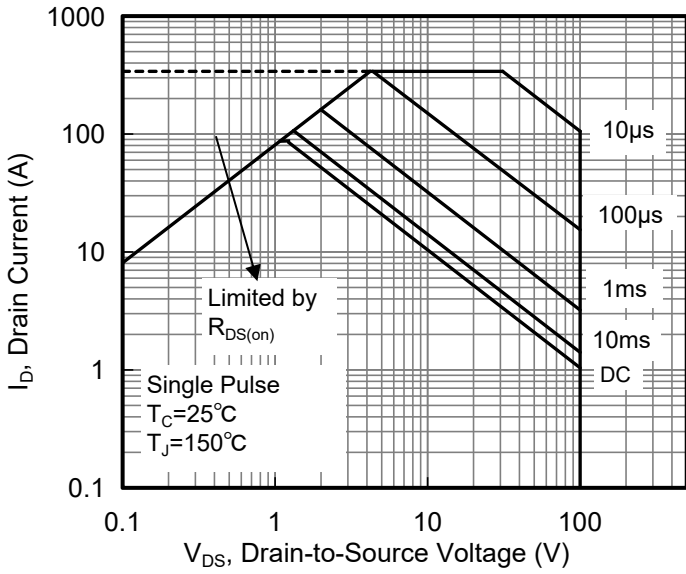
**Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>J</sub>=25°C (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.7	2.4	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =40A	--	6.8	8.3	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	--	2902	--	pF
C <sub>oss</sub>	Output Capacitance		--	230	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	7.5	--	pF
R <sub>g</sub>	Gate Resistance	f=1MHz	--	2.6	--	Ω
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =40A, V <sub>GS</sub> =10V	--	40	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	15.1	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	5.1	--	nC
<b>Switching Characteristics</b>						
T <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =50V, I <sub>D</sub> =40A, R <sub>G</sub> =6Ω, V <sub>GS</sub> =10V	--	10	--	ns
T <sub>r</sub>	Turn-on Rise Time		--	6	--	ns
T <sub>d(off)</sub>	Turn-Off Delay Time		--	51	--	ns
T <sub>f</sub>	Turn-Off Fall Time		--	9	--	ns
<b>Source- Drain Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)</b>						
I <sub>SD</sub>	Source-Drain Current (Body Diode)		--	--	85	A
V <sub>SD</sub>	Forward on voltage	I <sub>S</sub> =40A, V <sub>GS</sub> =0V	--	--	1.2	V
T <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C, I <sub>F</sub> =40A, di/dt=100A/μs	--	95	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	110	--	nC

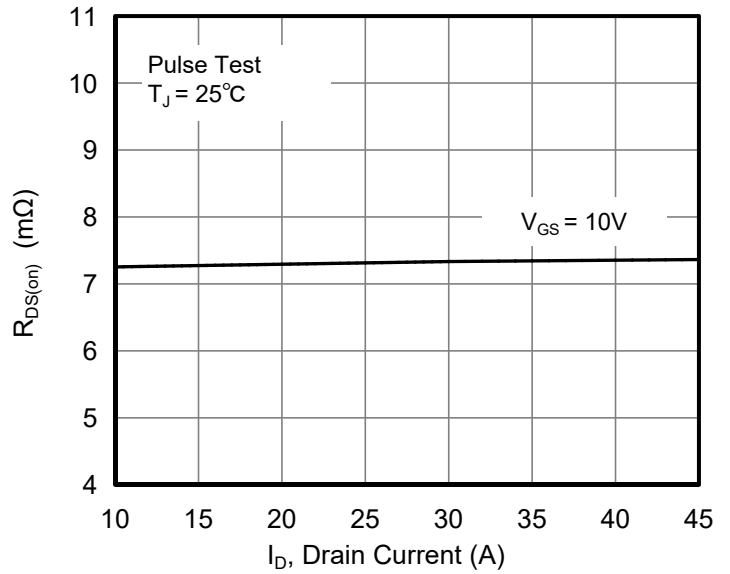
**Notes**

1. L=0.5mH, V<sub>DD</sub>=50V, Start T<sub>J</sub>=25°C.
2. Limited by maximum junction temperature.
3. Repetitive Rating: Pulse width limited by maximum junction temperature.

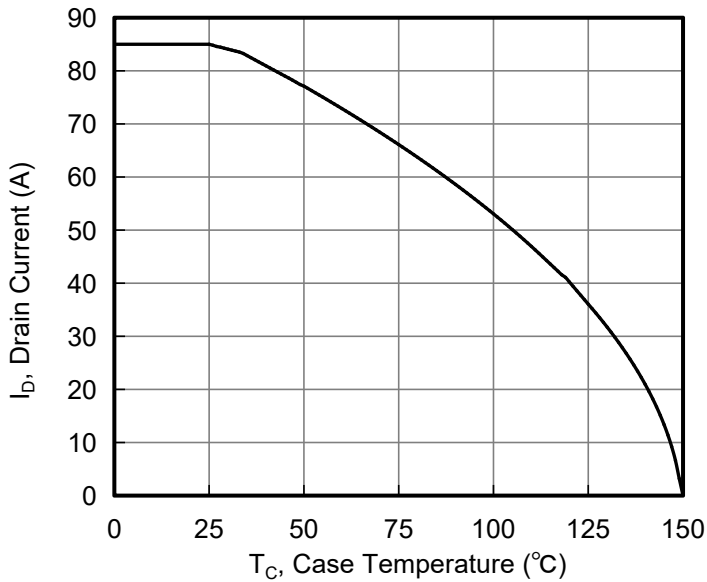
**Typical Characteristics**  $T_J = 25^\circ\text{C}$ , unless otherwise noted



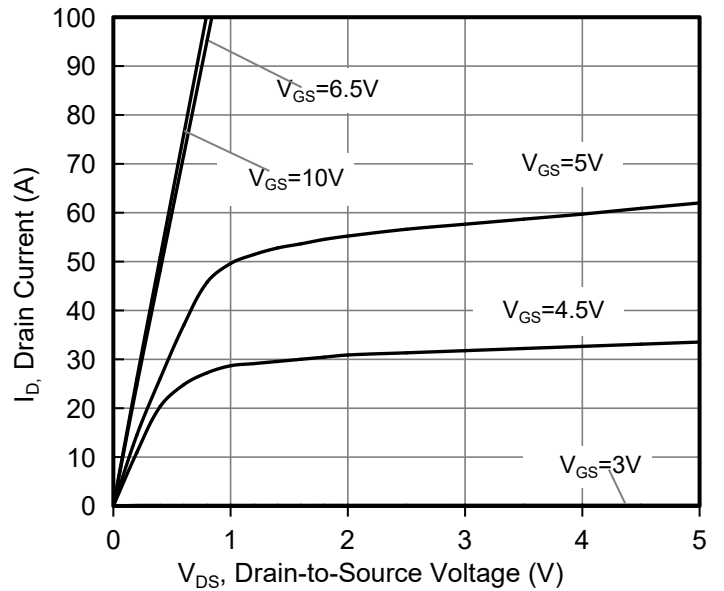
**Figure 1. Maximum Safe Operating Area**



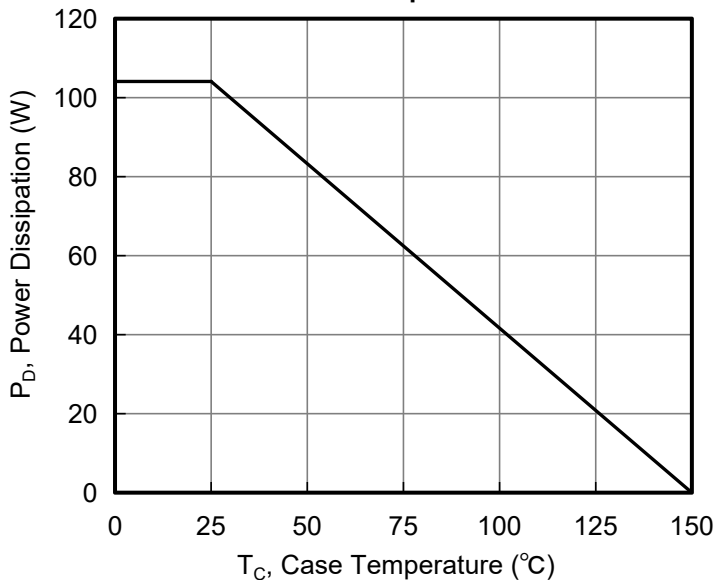
**Figure 4. Drain-to-Source On Resistance vs Drain Current**



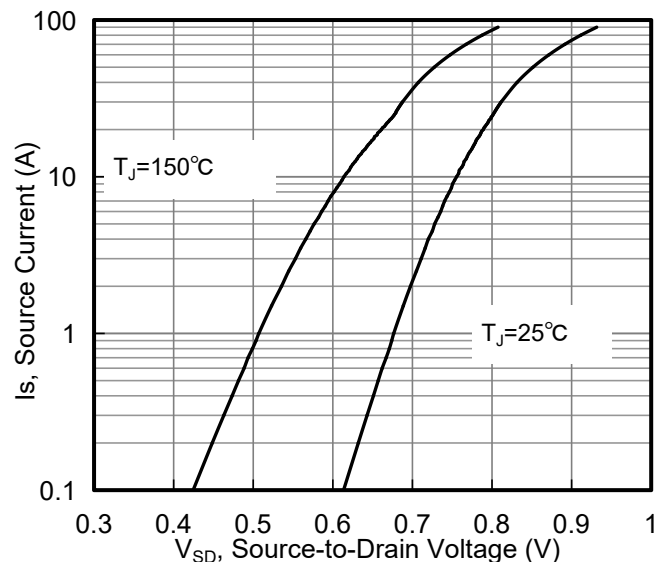
**Figure 2. Maximum Continuous Drain Current vs Case Temperature**



**Figure 5. Typical output Characteristics**



**Figure 3. Maximum Power Dissipation vs Case Temperature**



**Figure 6. Typical Body Diode Transfer Characteristics**

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

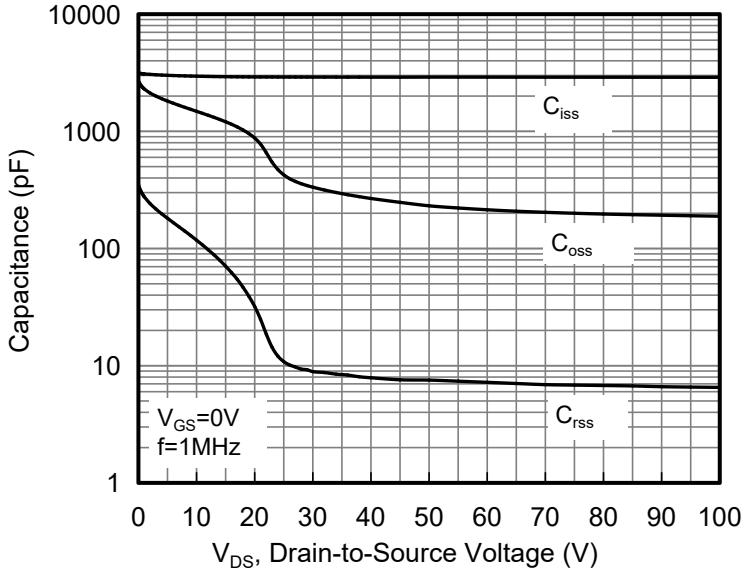


Figure 7. Capacitance Characteristics

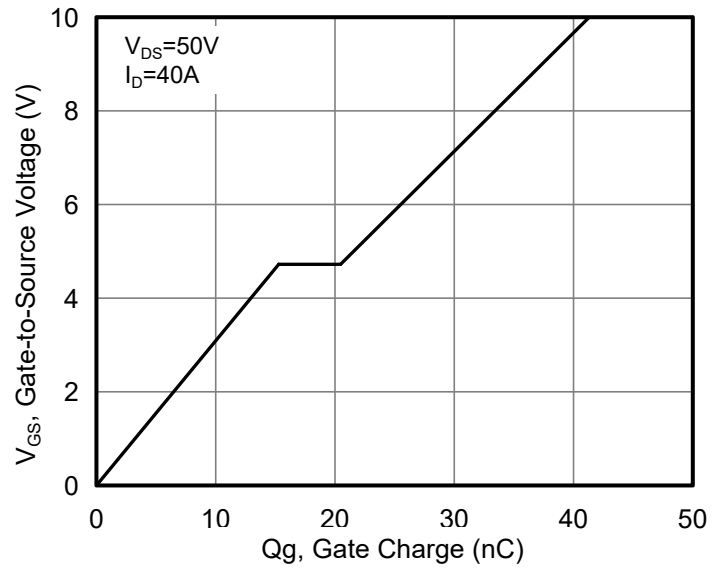


Figure 10. Typical Gate Charge vs Gate to Source Voltage

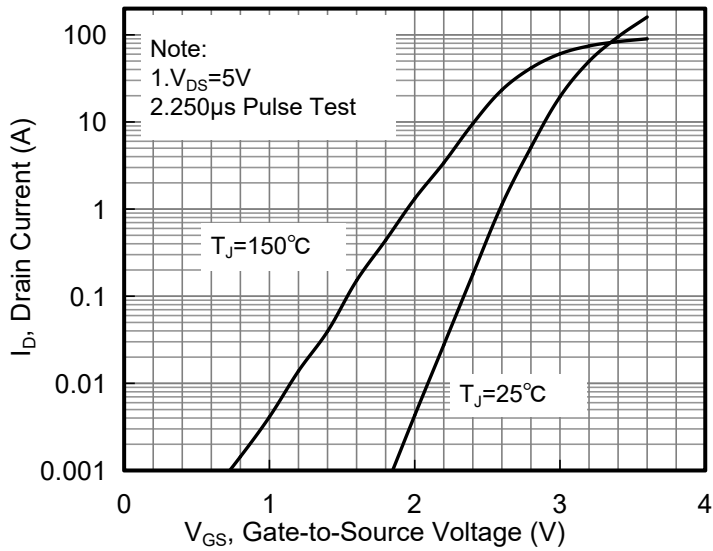


Figure 8 Typical Transfer Characteristics

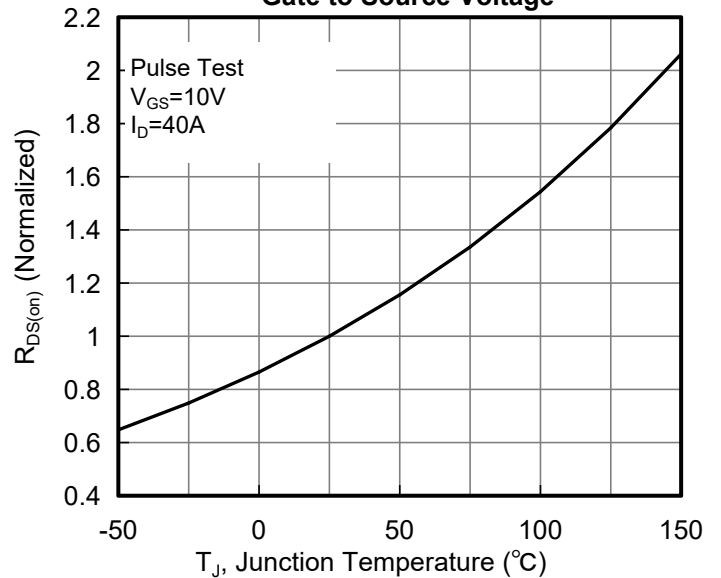


Figure 11. Normalized On Resistance vs Junction Temperature

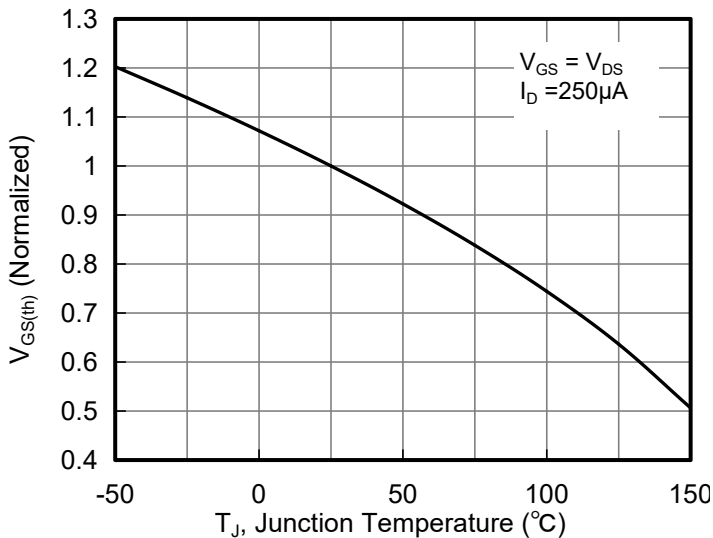


Figure 9 . Normalized Threshold Voltage vs Junction Temperature

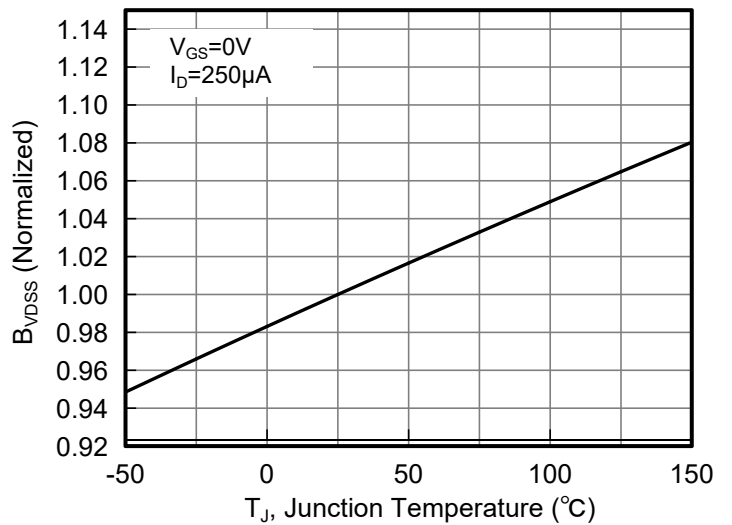


Figure 12. Normalized Breakdown Voltage vs Junction Temperature

Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

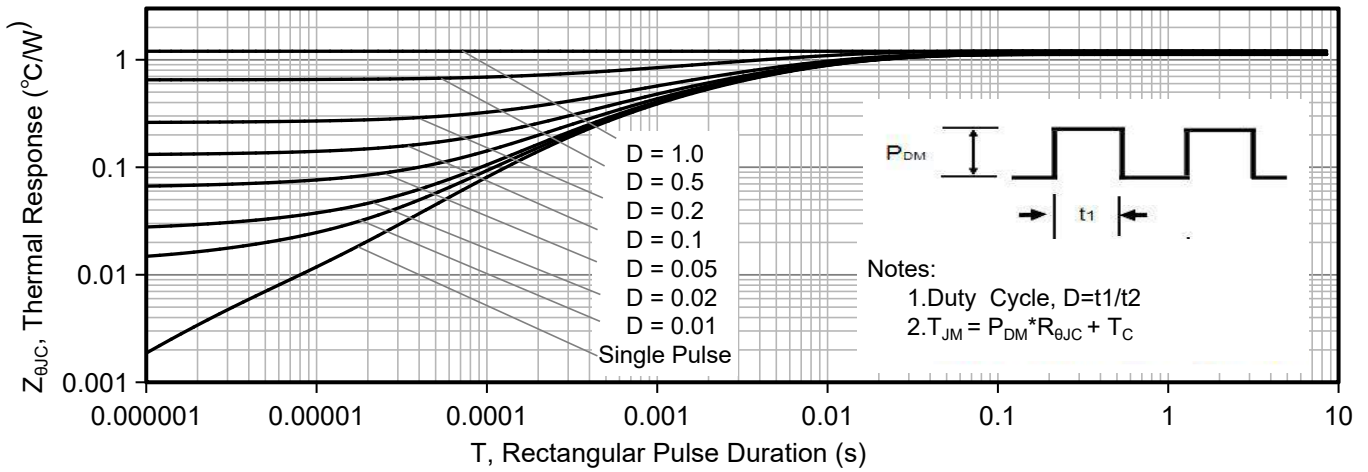


Figure 13. Maximum Effective Thermal Impedance , Junction to Case

Figure A: Gate Charge Test Circuit and Waveform

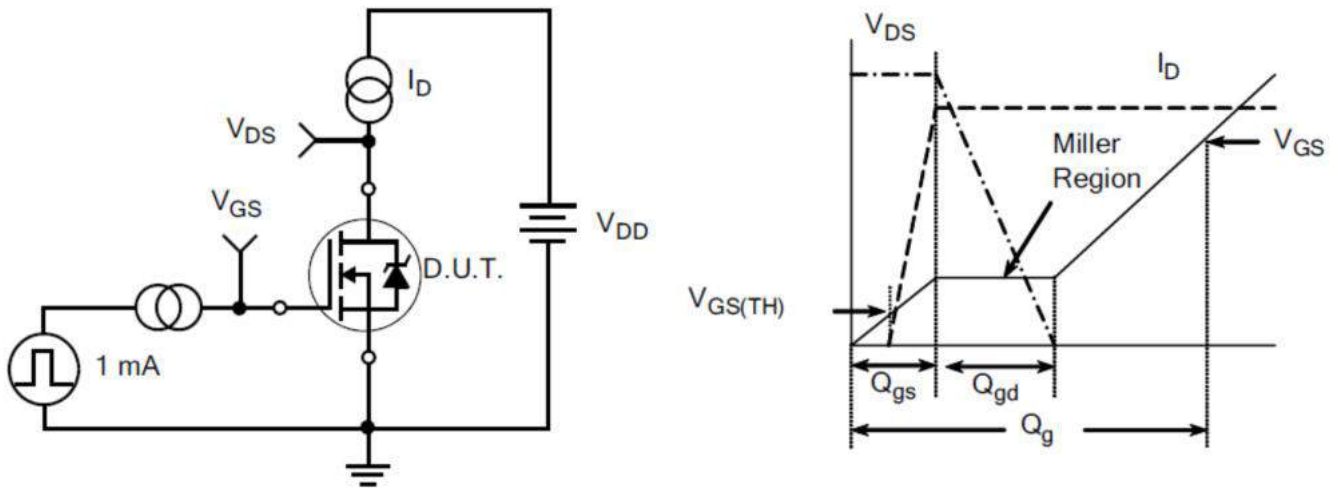


Figure B: Resistive Switching Test Circuit and Waveform

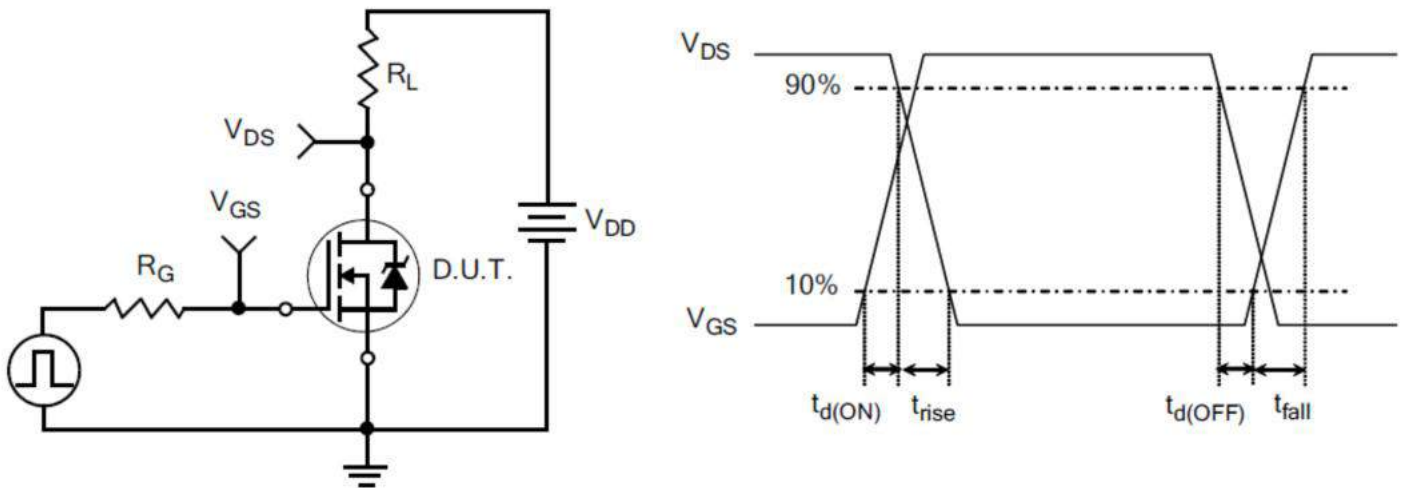
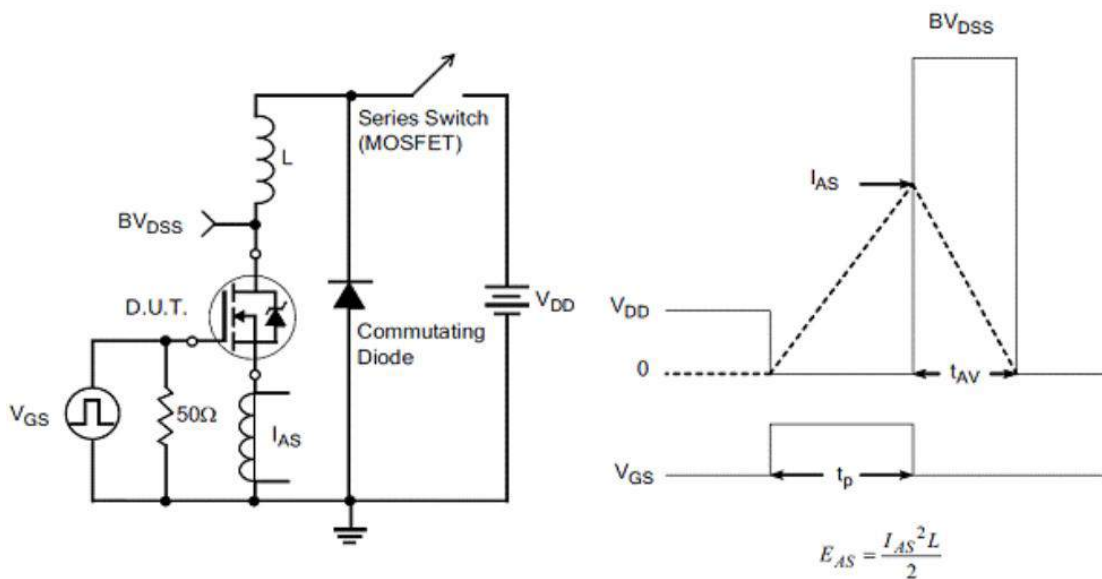
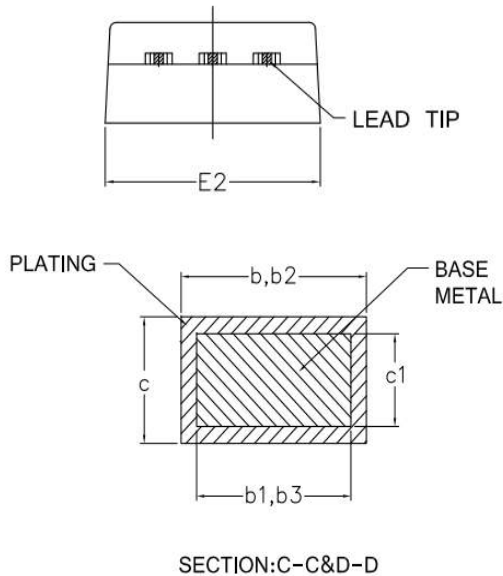
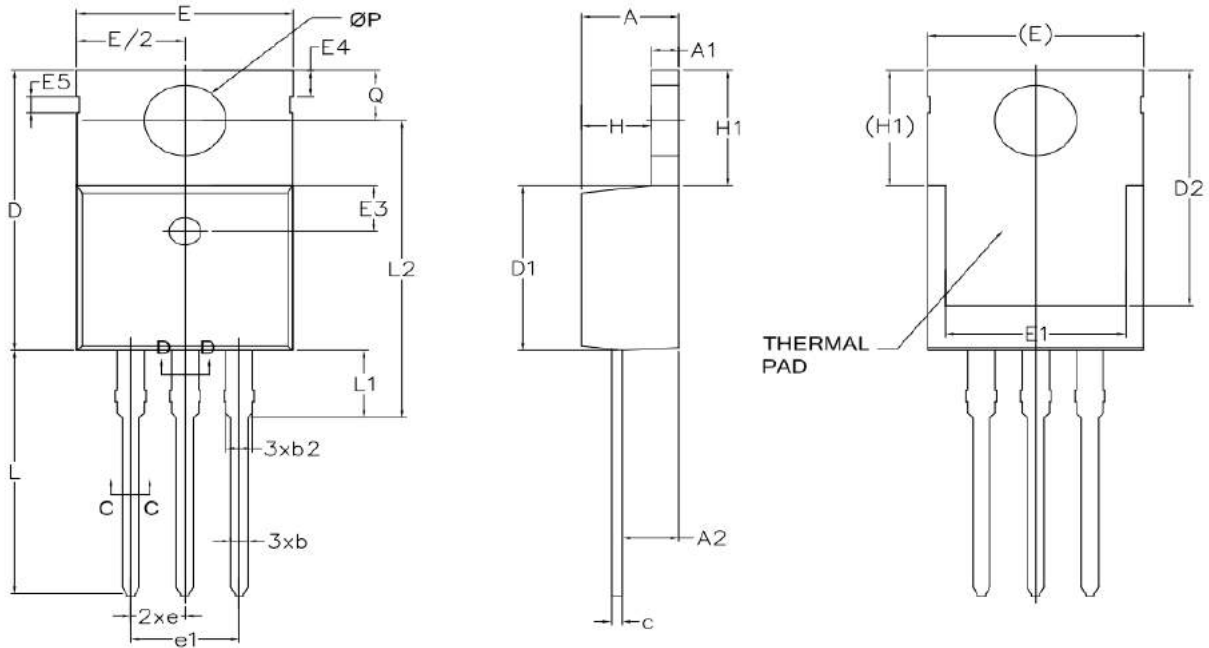


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



## TO-220-3L Package Information



SYMBOLS	COMMON		
	MM		
	MIN.	NOM.	MAX.
A	4.47	4.57	4.67
A1	1.20	1.30	1.40
A2	2.35	2.67	2.90
b	0.71	0.80	0.91
b1	0.71	0.80	0.86
b2	1.22	1.27	1.36
b3	1.22	1.27	1.31
c	0.47	0.50	0.60
c1	0.47	0.50	0.55
D	14.70	15.30	15.80
D1	8.90	9.00	9.47
D2	11.75	/	13.60
E	9.70	/	10.37
E1	7.00	8.44	8.89
E2	9.80	10.11	10.20
E3	2.40	2.50	2.60
E4	1.27	1.42	1.57
E5	0.90TYP		
e	2.54BSC		
e1	5.08BSC		
H	3.00	3.27	3.40
H1	6.15	6.30	6.45
L	12.90	13.45	14.80
L1	2.54	3.69	3.84
L2	12.13	16.25	16.5
∅P	3.60	3.84	3.90
Q	2.65	2.74	2.95

## Customer Service

Sales and Service:

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